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(54) SEMICONDUCTOR DEVICE

to a plurality of vias 44 of the wiring substrate 4.

(57) Abstract:

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PROBLEM TO BE SOLVED: To provide a semiconductor device for thinning a package, while keeping high reliability for each laminated IC chip in a stacked-type CSP.

SOLUTION: An IC chip 1 is in a flip-chip form. A main surface side is exposed to the outside as a mounting surface, and a pad 12 is provided with an external terminal 13. The IC chip 2 in a sealing member 6 is laminated on the reverse side of the IC chip 1 via an insulation adhesive member 3. A wiring substrate 4 related to the IC chip 2 is provided around the IC chip 1. The wiring substrate 4 includes a base material 41 and an insulation film 43 which accompany a conductive pattern 42 at the upper portion. The prescribed part of the conductive pattern 42 is connected to each of the pad 21 of the IC chip 2, for example, by a bonding wire 5. An external terminal 45 of the IC chip 2 is connected

